

VERSION

No.	Version	Date	Details	Name	Check
1	V1.0.0	2020/7/20	Initial	wangcheng	
2	V1.0.1				

PCB Process Description

Board Thickness	1.0mm
Base material	Copper-clad laminate
Copper Thickness	1 oz
Pad Processing	HAL&SMOBC
Solder/Mask	

Title		
Size	Number	Revision
C		
Date:	2020/12/31	Sheet of
File:	11 work\01 VER SchDoc	Drawn By

	1	2	3	4	5	6
A						A
B						B
C						C
D						D
	1	2	3	4	5	6

Title		
Size	Number	Revision
C		
Date:	2020/12/31	Sheet of
File:	11-work-02-Block Diagram.SchDoc	Drawn By

	1	2	3	4	5	6
A						A
B						B
C						C
D						D
	1	2	3	4	5	6

Title		
Size	Number	Revision
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Date:	2020/12/11	Sheet of
Fig:	11-work-03 SYS POWER TREE.SchDoc Drawn By:	



